- **State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}**
- **High-Impedance State During Power Up and Power Down**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Designed to Facilitate Incident-Wave Switching for Line Impedances of 25 Ω or Greater**
- **Distributed V_{CC} and GND Pins Minimize Noise Generated by the Simultaneous Switching of Outputs**
- **Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic 300-mil DIPs (NT)**

DW OR NT PACKAGE
(TOP VIEW)

1Y1	1		24	1$\overline{OE}$
GND	2		23	1A1
1Y2	3		22	1A2
1Y3	4		21	V_{CC}
GND	5		20	1A3
1Y4	6		19	1A4
2Y1	7		18	2A1
GND	8		17	2A2
2Y2	9		16	V_{CC}
2Y3	10		15	2A3
GND	11		14	2A4
2Y4	12		13	2$\overline{OE}$
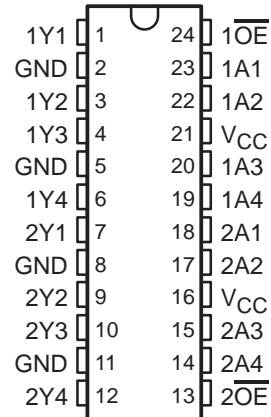
description

The SN64BCT25244 is a 25-Ω octal buffer and line driver designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented transceivers.

When the output-enable (1$\overline{OE}$ and 2$\overline{OE}$) inputs are low, the device transmits data from the A inputs to the Y outputs. When 1$\overline{OE}$ and 2$\overline{OE}$ are high, the outputs are in the high-impedance state.

This buffer/driver is capable of sinking 188-mA I_{OL}, which facilitates switching 25-Ω transmission lines on the incident wave. The distributed V_{CC} and GND pins minimize switching noise for more reliable system operation.

The outputs are in a high-impedance state during power up and power down while the supply voltage value is less than approximately 3 V.

The SN64BCT25244 is characterized for operation from −40°C to 85°C and 0°C to 70°C.

FUNCTION TABLE
(each buffer/driver)

| INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

TEXAS INSTRUMENTS

logic symbol†

logic diagram (positive logic)
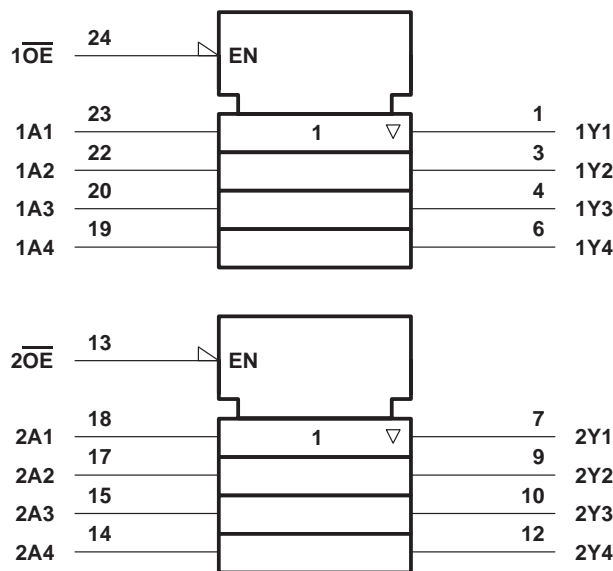
† This symbol is in accordance with ANSI/IEEE Std 91-1984
   and IEC Publication 617-12.
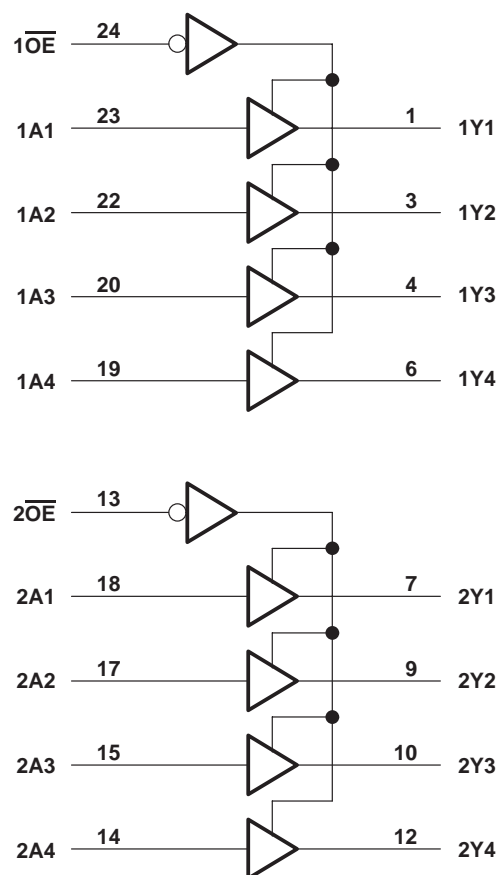
absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} .... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) .... −0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, V_O .... −0.5 V to 5.5 V
Voltage range applied to any output in the high state, V_O .... −0.5 V to V_{CC}
Input clamp current, I_{IK} ($V_I < 0$) .... −30 mA
Current into any output in the low state, I_O .... 376 mA
Operating free-air temperature range .... −40°C to 85°C
Storage temperature range .... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and
   functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not
   implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

TEXAS INSTRUMENTS

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I_{IK}	Input clamp current			−18	mA
I_{OH}	High-level output current			−80	mA
I_{OL}	Low-level output current			188	mA
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP[†]	MAX	UNIT
V_{IK}	V_{CC} = 4.5 V,	I_I = −18 mA			−1.2	V
V_{OH}	V_{CC} = 4.75 V,	I_{OH} = − 3 mA	2.7			V
	V_{CC} = 4.5 V,	I_{OH} = −80 mA	2			
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 94 mA		0.42	0.55	V
		I_{OL} = 188 mA			0.7	
I_{OZ}	V_{CC} = 0 to 2.3 V (power up)	V_O = 2.7 V or 0.5 V, $\overline{OE}$ at 0.8 V			±50	µA
	V_{CC} = 2.3 to 0 (power down)				±50	
I_I	V_{CC} = 5.5 V,	V_I = 5.5 V			0.1	mA
I_{IH}	V_{CC} = 5.5 V,	V_I = 2.7 V			20	µA
I_{IL}	V_{CC} = 5.5 V,	V_I = 0.5 V			−0.6	mA
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V			50	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V			−50	µA
I_{CCL}	V_{CC} = 5.5 V,	Outputs open		90	119	mA
I_{CCH}	V_{CC} = 5.5 V,	Outputs open		59	78	mA
I_{CCZ}	V_{CC} = 5.5 V,	Outputs open		7	11	mA
C_i	V_{CC} = 5 V,	V_I = 2.5 V or 0.5 V		5.5		pF
C_o	V_{CC} = 5 V,	V_O = 2.5 V or 0.5 V		17		pF

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			T_A = −40°C to 85°C		T_A = 0°C to 70°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	3.2	4.9	1	5.6	1	5.5	ns
t_{PHL}			2	4	5.6	2	6.3	2	6	
t_{PZH}	$\overline{OE}$	Y	3.2	5.6	8.5	3.2	9.7	3.2	9.3	ns
t_{PZL}			3.7	6.3	9.2	3.7	10.4	3.7	10.2	
t_{PHZ}	$\overline{OE}$	Y	1.6	3.6	5.5	1.6	6.5	1.6	6.3	ns
t_{PLZ}			3.1	5.3	7.8	3.1	9.5	3.1	8.4	

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN64BCT25244DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN64BCT25244DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN64BCT25244DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN64BCT25244DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN64BCT25244DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN64BCT25244DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN64BCT25244DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN64BCT25244NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN64BCT25244NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN64BCT25244NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN64BCT25244NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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